



Material Content Data Sheet



Sales Product Name		IPB025N08N3 G		Issued		29. August 2013		
MA#		MA000405262						
Package		PG-TO263-3-2		Weight*		1467.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.286	0.84	0.84	8373	8373
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		581	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174	
	non noble metal	copper	7440-50-8	851.691	58.02	58.10	580385	581141
wire	non noble metal	aluminium	7429-90-5	11.932	0.81	0.81	8131	8131
encapsulation	organic material	carbon black	1333-86-4	8.619	0.59		5874	
	plastics	epoxy resin	-	94.810	6.46		64609	
	inorganic material	silicondioxide	60676-86-0	471.178	32.11	39.16	321085	391567
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6581	6581
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	non noble metal	tin	7440-31-5	0.119	0.01		81	
	noble metal	silver	7440-22-4	0.149	0.01		101	
	non noble metal	lead	7439-92-1	5.678	0.39	0.41	3869	4051
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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